



Box-PC

GOLUB 7000-DE

- Supporting Intel® 9th/ 8th-Gen CPU
- Up to 64GB DDR4 2666/ 2400 SDRAM (two SODIMM slots)
- Fanless

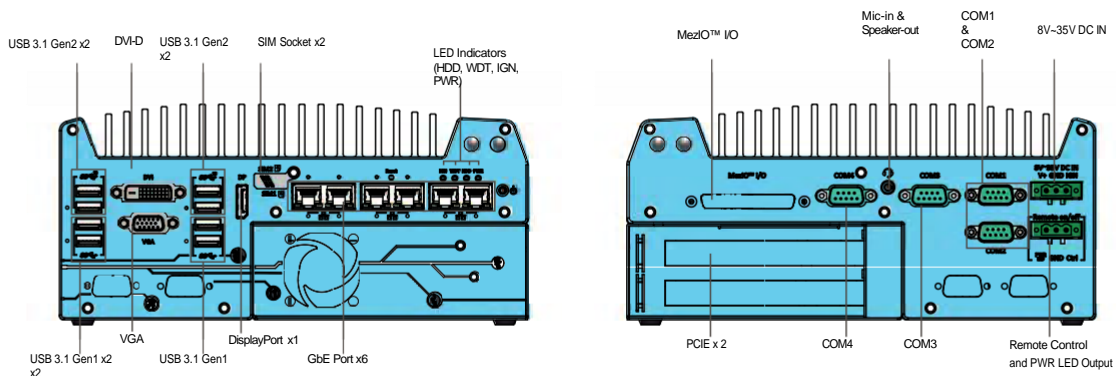


*Attention barebone system:

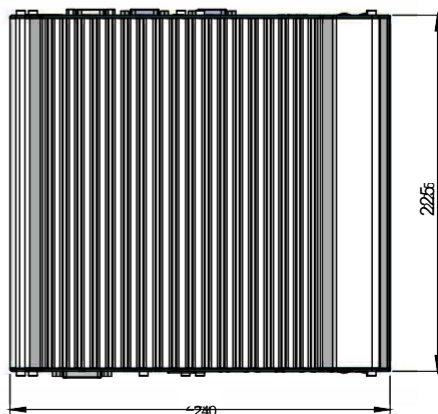
CPU, RAM, HDDs / SSDs, operating systems and expansion modules can be found in the catalog under "System components and accessories": https://downloads.aprotech.de/cms/catalogue/APROtech_catalogue.pdf
 You will receive a link to the catalog with prices from your sales contact: <https://aprotech.de/en>

CPU*	Supporting Intel® 9 th / 8 th -Gen CPU (LGA1151 socket, 65W/ 35W TDP)
Chipset	Intel® Q370
Graphics	Integrated Intel® UHD graphics 630
RAM*	Up to 64GB DDR4 2666/ 2400 SDRAM (two SODIMM slots)
Storage interface*	2x internal SATA port for 2.5" HDD/ SSD installation, supporting RAID 0/ 1 1x M.2 2280 M key socket (PCIe Gen3 x4) for NVMe SSD or Intel® Optane™ memory installation 1x full-size mSATA port (mux with mini-PCIe)
Ports	2x GigE, 1x Intel® I219, 1x Intel® I210; 6x GigE, 1x Intel® I219, 5x Intel® I210 Option: IEEE 802.3at PoE+ PSE for Port 3 - Port 6 100W total power budget 4x USB 3.1 Gen2 (10 Gbps) 4x USB 3.1 Gen1 (5 Gbps) 2x software-programmable RS-232/422/485 ports (COM1/ COM2) 2x RS-232 ports (COM3/ COM4) 1x VGA, supporting 1920 x 1200 resolution 1x DVI-D, supporting 1920 x 1200 resolution 1x DisplayPort, supporting 4096 x 2304 resolution 1x 3.5 mm jack for mic-in and speaker-out
Expanded interface*	2x PCIe x8 slots@Gen3, 4-lanes PCIe signals in Cassette 1x full-size mini-PCIe socket with internal SIM socket (mux with mSATA) 1x M.2 2242 B key socket with dual front-accessible SIM sockets, supporting dual SIM mode with selected M.2 LTE module
MezIO™ interface	1x MezIO™ expansion port for MezIO™ modules
Cooling system	Passive, fanless

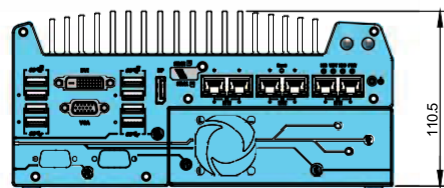
Power input	1x 3-pin pluggable terminal block for 8V to 35VDC input 1x 3-pin pluggable terminal block for remote control and PWR LED output
Power consumption	TBA
Operating temperature	with 35W CPU -25 °C to 70 °C* with 65W CPU -25 °C to 70 °C* (configured as 35W TDP) -25 °C to 50 °C* (configured as 65W TDP)
Storage temperature	-40 ° to 85 °C
Storage humidity	10% to 90%; non-condensing
Vibration	Operating, MIL-STD-810G, Method 514.6, Category 4
Shock	Operating, MIL-STD-810G, Method 516.6, Procedure I, Table 516.6-II
Certificate	CE/FCC Class A, according to EN 55032 & EN 55024; UL62368-1, IEC62368-1
Protection class	IP20
Mounting	Wall mounting; option: Rack mounting; DIN-Rail
Operating system	Option: Microsoft Windows® 10 (x64); Fedora 29; Ubuntu 16.04.5 LTS & Ubuntu 18.04.0 LTS
Dimensions / mm	240 x 225 x 110.5
Weight / kg	ca. 3.7
Scope of delivery	2x 3-pin terminal connector; Rubber absorber; Driver CD; Wall mounting kit



Dimensions



Unit : mm



* For sub-zero operating temperature, a wide temperature HDD drive or Solid State Disk (SSD) and RAM are required.

Order Information

GOLUB 7000-DE, 2x PCIe, 2x GigE	650062.3
GOLUB 7000-DE, 2x PCIe, 6x GigE	650062.1
GOLUB 7000-DE, 2x PCIe, 6x GigE, 4x PoE+	650062.2
MezIO™ Kit G4, 4x GigE	750010.1
MezIO™ Kit G4P, 4x GigE w/PoE+ (only in connection with part no. 650062.2)	750010.5
MezIO™ Kit U3_4, 4x USB3.0	750015.2
MezIO™ Kit V20-B, Ignition Power Control	750018.2
MezIO™ Kit C180-B, 4x RS-232/422/485, 4x RS-232	750019.1
MezIO™ Kit C181-B, 4x RS-232/422/485, 4x RS-422/485	750019.3
MezIO™ Kit D220-B, 8-CH isolated DI/8-CH isolated DO	750020.1
MezIO™ Kit D230-B, 16-CH isolated DI/16-CH isolated DO	750020.3
Option Rack mounting kit	740040.12
Option DIN-Rail mounting kit	740040.8

***Attention barebone system:**

CPUs, RAM, HDDs / SSDs, operating systems and expansion modules can be found in the catalog under "System components and accessories": https://downloads.aprotech.de/cms/catalogue/APROtech_catalogue.pdf
You will receive a link to the catalog with prices from your sales contact: <https://aprotech.de/en>